

In the Specification:

Amend paragraph [0001] as follows:

1 **[0001]** This application is a continuation of United States patent application
2 serial number 10/036,579 filed December 31, 2001 now United States patent number
3 6,651,864 issued November 25, 2003 entitled "Dissipative Ceramic Bonding Tool Tip"
4 which claims the priority benefit of United States provisional patent application serial
5 number 60/288,203 filed May 1, 2001 entitled "Dissipative Ceramic Bonding Tip" and is
6 also a continuation-in-part of United States patent application serial number 09/514,454
7 filed February 25, 2000 now United States patent 6,354,479 issued March 12, 2002
8 entitled, "Dissipative Ceramic Bonding Tool Tip," which claims the priority benefit of
9 United States provisional patent application serial number 60/121,694 filed February 25,
10 1999 entitled "Dissipative Ceramic Bonding Tool Tip." The contents of the above
11 applications are incorporated herein by reference.